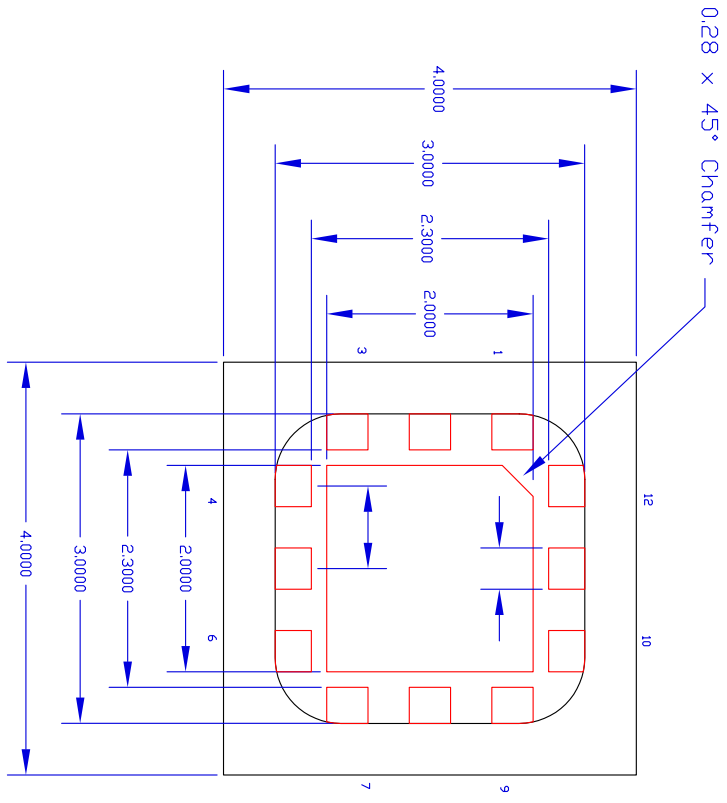
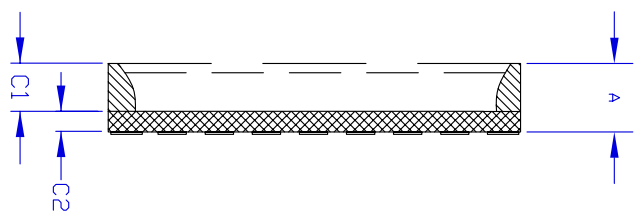


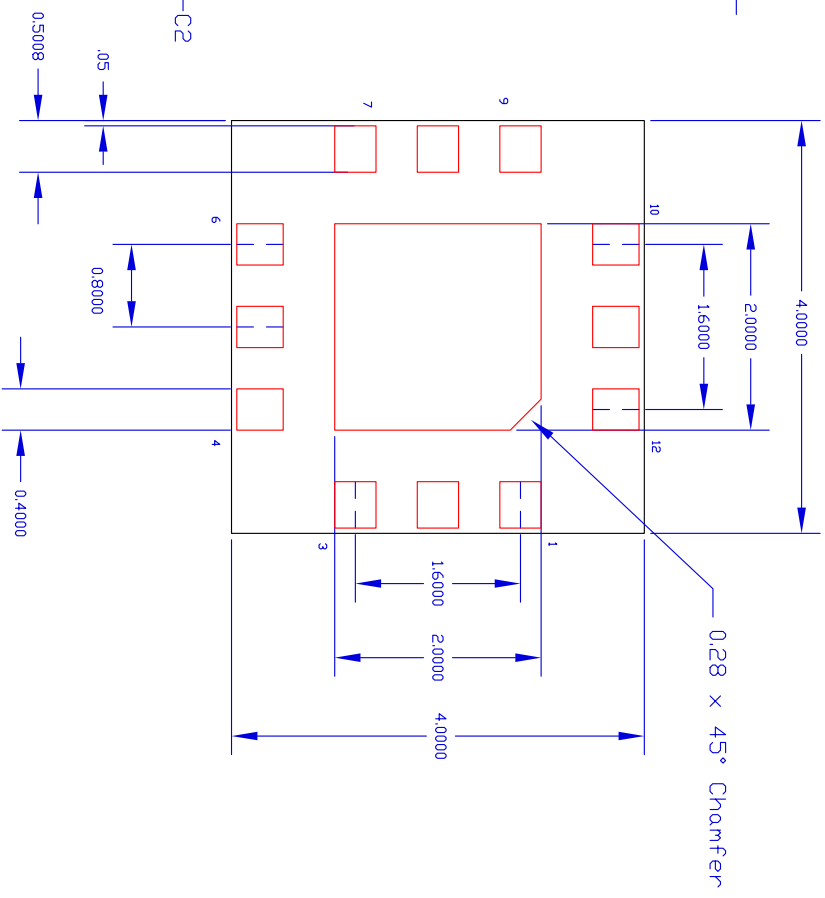
TOP VIEW



SIDE VIEW

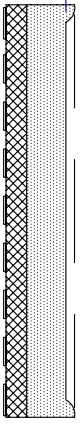


BOTTOM VIEW



Cavity wall variance 0.05~0.15

SIDE VIEW



HEIGHT TABLE			
SERIES	C1	C2	A
A-QFN	0.63	0.27	0.90
A-TQFN	0.38	0.27	0.65
TOL	+/- 0.10	+/- 0.05	+/- 0.15

OTHER SIZES AVAILABLE

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Note:

- Organic substrate
- Cavity Dam: Hysol FP4451TD
- Pads: Cu/Ni/Au
- Copper Thickness: 12µm~18µm (0.5~0.7mil)
- Bonding Pad Gold Thickness: 1.3µm (50 micro-inch)
- PCB Pads Gold Thickness: 0.13µm (5 micro-inch)
- Nickel Thickness: 38µm (150 micro-inch)
- All Dimensions Are mm

TOLERANCES UNLESS NOTED:		APPROVALS		DATE	
X.XX	±			11/29/08	
X.XXX	±				
X.XXXX	±				
ALL DIMENSIONS ARE IN:		DRAWN		TA	
□ INCHES □ MILLIMETERS		ENG			
ANGLES ±		MFG			
THIRD ANGLE PROJECTION:		QA		TITLE	
□		CUST		12-LEAD 4MM P=0.80MM	
REVISED		SCALE		A-QFN (AIR) OPEN CAVITY	
		NONE		SIZE	
		A		DRAWING NO.	
		481210		REV	
		DO NOT SCALE DRAWING		A	
		SHEET		1 OF 1	

